DLAP-3000-CF Series

Embedded System supporting
MXM Graphics Module with
8th/9th Generation Intel® Core™
i7/i5/i3 in LGA1151 Socket



Features

- ADLINK MXM Graphics module support (Type A/B, up to 120W)
- 8th/9th Gen Intel® Core™ i7/i5/i3, Celeron® processor
- Dual SODIMMs for up to 64GB DDR4 non-ECC memory (dependent on CPU)
- DisplayPort (2 from CPU, 4 from MXM)
- Reliable Molex type 12V DC-in connector

Software Support

- Win10 IoT Enterprise SAC 64bit
- Ubuntu 18.04.1 LTS 64bit

Optional Accessories

- CPU cooler: 32-20378-0000-A0
- CPU cooler bracket: 32-50015-0100-A0
- MXM cooler for A1000/A2000: 32-20932-0000-A0
- MXM cooler for RTX5000: 32-20839-1000-A0
- MXM cooler for T1000: 32-20830-0200-A0
- MXM cooler for RTX3000: 32-20823-1100-A0
- 12V/240W adaptor: 31-62164-0010-A0
- Wall Mount Bracket: 34-34546-0000-A0 2pcs
- Wifi Kit INTEL AC9260 Non-VPRO: 991-95266-0020
- DLAP-3000 AC/DC power supply kit, 500W (12V/41.7A): 91-95296-001E

Ordering Information

Model	MXM Support	Chipset	DC-in
DLAP-3000-CFP12	EGX-MXM-A1000/A2000/ T1000/RTX3000/RTX5000 (not incl.)	H310	12V
DLAP-3000-CFT1	EGX-MXM-T1000	H310	12V
DLAP-3000-CFT3	EGX-MXM-RTX3000	H310	12V
DLAP-3000-CFT5	EGX-MXM-RTX5000	H310	12V

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Specifications

Model	DLAP-3000-CFP1	DLAP-3000-CFP2	DLAP-3000-CFT1	DLAP-3000-CFT3	DLAP-3000-CFT5
	DLAP-3000-CFP12*				
MXM Support	EGX-MXM-P1000	EGX-MXM-P2000	EGX-MXM-T1000	EGX-MXM-RTX3000	EGX-MXM-RTX5000
Processor	Intel® Core™ i7-9700E, 2.6GHz, 12M Cache, 65W TDP, LGA1151, DDR4 2666MHz support (8C/8T) Intel® Core™ i7-9700TE, 1.8GHz, 12M Cache, 35W TDP, LGA1151, DDR4 2666MHz support (8C/8T) Intel® Core™ i5-9500E, 3.0GHz, 9M Cache, 65W TDP, LGA1151, DDR4 2666MHz support (6C/6T) Intel® Core™ i5-9500TE, 2.2GHz, 9M Cache, 35W TDP, LGA1151, DDR4 2666MHz support (6C/6T) Intel® Core™ i3-9100E, 3.1GHz, 6M Cache, 65W TDP, LGA1151, DDR4 2400MHz support (4C/4T) Intel® Core™ i3-9100TE, 2.2GHz, 6M Cache, 35W TDP, LGA1151, DDR4 2400MHz support (4C/4T) Intel® Core™ i7-8700, 3.2GHz, 12M Cache, 65W TDP, LGA1151, DDR4 2666MHz support (6C/12T) Intel® Core™ i7-8700T, 2.4GHz 12M Cache, 35W TDP, LGA1151, DDR4 2666MHz support (6C/12T) Intel® Core™ i5-8500, 3.0GHz, 9M Cache, 65W TDP, LGA1151, DDR4 2666MHz support (6C/6T) Intel® Core™ i5-8500T, 2.1GHz, 9M Cache, 35W TDP, LGA1151, DDR4 2666MHz support (6C/6T) Intel® Core™ i3-8100, 3.6GHz, 6M Cache, 65W TDP, LGA1151, DDR4 2400MHz support (4C/4T) Intel® Celeron® G4900, 3.1GHz, 2M Cache, 54W TDP, LGA1151, DDR4 2400MHz support (2C/2T) Intel® Celeron® G4900T, 2.9GHz, 2M Cache, 35W TDP, LGA1151, DDR4 2400MHz support (2C/2T)				
Chipset	Intel® H310 Chipset				
Memory	Non-ECC DDR4 2666/2400MHz, 2x SO-DIMM, up to 64GB (dependent on CPU)				
I/O Interfaces					
Display	6x DisplayPort (2 from CPU, 4 from MXM)				
Ethernet	1x GbE (Intel® i219-LM), 3x GbE (Intel® i210-AT)				
Serial Ports	1x RS-232/422/485, 1x RS-232				
USB	4x USB 3.2 Gen1 x1 ports, 4x USB 2.0 ports				
M.2	1x M.2 E key supporting 1630 or 2230 for Wi-Fi/BT module, 1x M.2 B key supporting 2242 or 2280 for Wi-Fi/BT module				
Digital IO	Default: w/o DIO Optional: 1x DI/DO with 4 in, 4 out Note: Optional DIO, Audio and TPM 2.0 must be chosen together.				
Audio	Default: w/o Audio Option 1: Mic-in, Line-out, Line-in Option 2: Mic-in, L/R speaker-out (6W + 6W) Option 3: Line-in, L/R speaker-out (6W + 6W)				
TPM 2.0	Default: w/o TPM				
eSIM	Optional				
Storage					
SATA	2x 2.5" SATA 6Gb/s external drive bays 1x SATA 6Gb/s signal via M.2 B key connector				
Mechanical					
Dimensions	235 x 182 x 75mm (W x D x H, without foot pads)				
Mounting	Optional wall-mount bracket				
Power Supply					
DC Input	DC 12V input (Molex DC-in jack)				
AC Input	Optional: 240W (12V/20A) AC/DC adapter Optional: 500W (12V/41.7A) AC/DC power supply unit				
Environmental					
Operating Temperature	0°C to 50°C (W/MXM module except RTX-5000, W/SSD 0°C to 40°C (W/MXM RTX-5000, W/SSD)				
Storage Temperature	-20°C to 70°C				
Humidity	5% to 95%, non-condensing				
Vibration	Operating vibration: 2Grms, 5-500Hz, 3 axes, Package(NON-OP) vibration: 3.44Grms, 10-1000Hz, 3 axes (W/MXM, W/SSD)				
Operating and Package (NON-OP) shock	30G, 11ms duration, half sine (W/MXM, W/SSD)				
EMC	EN55032/35, EN61000-6-2/-4, CE, FCC Part 15B Class B (W/240W adaptor), Class A (W/500W PSU)				
Safety	UL/cUL and CB				

*Note: These models do not include an MXM graphics module.

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